

RELIABILITY REPORT





Reliability Data Report Product Family R017

LT1054

Reliability Data Report

Report Number: R017

Report generated on: Wed Jun 18 10:36:27 PDT 2014

OPERATING LIFE TEST					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS (+125°C) ¹	No. of FAILURES _{2,3}
SIDEBRAZE	105	9401	9747	165	0
HERMETIC	1378	8342	0343	3635	0
PLASTIC DIP	879	8701	9935	4561	0
SOIC/SOT/MSOP	89	9521	9526	316	0
Totals	2,451	-	-	8,677	0

HIGHLY ACCELERATED STRESS TEST AT +130 DEG C / 85% RH					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS (+85°C) ⁴	No. of FAILURES
PLASTIC DIP	150	9439	9712	410	0
SOIC/SOT/MSOP	3374	9223	0715	3318	0
Totals	3,524	-	-	3,728	0

PRESSURE COOKER TEST AT 15 PSIG , +121 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
PLASTIC DIP	804	9502	1103	45	0
SOIC/SOT/MSOP	2049	9504	0613	81	0
Totals	2,853	-	-	126	0

TEMP CYCLE FROM -65 TO 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
HERMETIC	17	0343	0343	1	0
CERDIP	49	9434	9434	4	0
PLASTIC DIP	1047	9233	1103	407	0
SOIC/SOT/MSOP	1441	9135	0613	183	0
Totals	2,554	-	-	595	0

THERMAL SHOCK FROM -65 TO 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
HERMETIC	17	0343	0343	0	0
PLASTIC DIP	544	9245	9907	270	0
SOIC/SOT/MSOP	1327	9135	0613	132	0
Totals	1,888	-	-	402	0

(1) Assumes Activation Energy = 1.0 Electron Volts
(2) Failure Rate Equivalent to +55 °C, 60% Confidence Level =0.21 FITS
(3) Mean Time Between Failure in Years = 540326.31
(4) Assumes 20X Acceleration from 85 °C to +130 °C
Note: 1 FIT = 1 Failure in One Billion Hours.
Note 2: HAST, Temp Cycle & Thermal Shock are subjected to J-STD-020 MSL1 Preconditioning